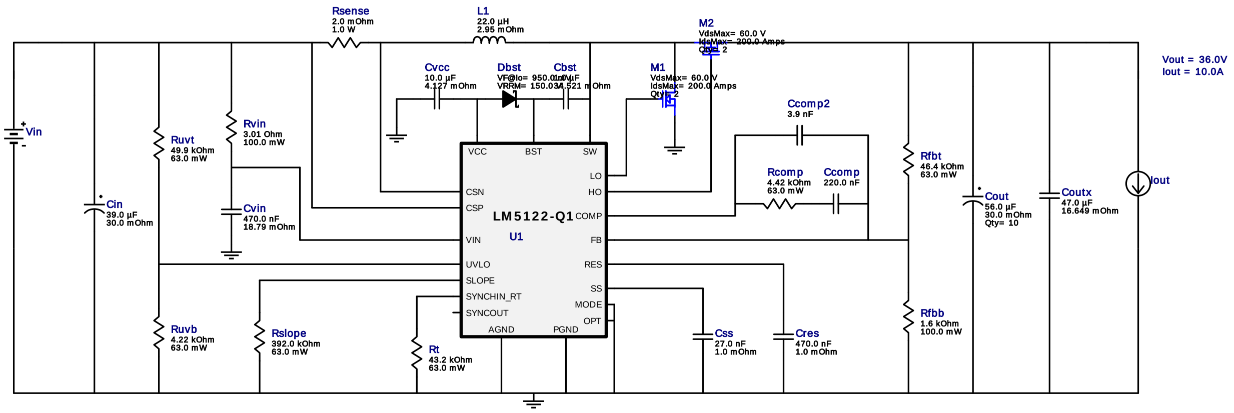
TEXAS INSTRUMENTS

WEBENCH ® Design Report

VinMin = 18.0V
VinMax = 24.0V
Vout = 36.0V
Iout = 10.0A

Device = LM5122QMH/NOPB
Topology = Boost
Created = 2026-01-17 05:07:51.755
BOM Cost = $29.93
BOM Count = 35
Total Pd = 9.22W

Design : 5 LM5122QMH/NOPB
LM5122QMH/NOPB 18V-24V to 36.00V @ 10A



1. This regulator device is qualified for Automotive applications. All passives and other components selected in this design may not be qualified for Automotive applications. The user is required to verify that all components in the design meet the qualification and safety requirements for their specific application.View WEBENCH(R) Disclaimer.

Design Alerts

Component Selection Information

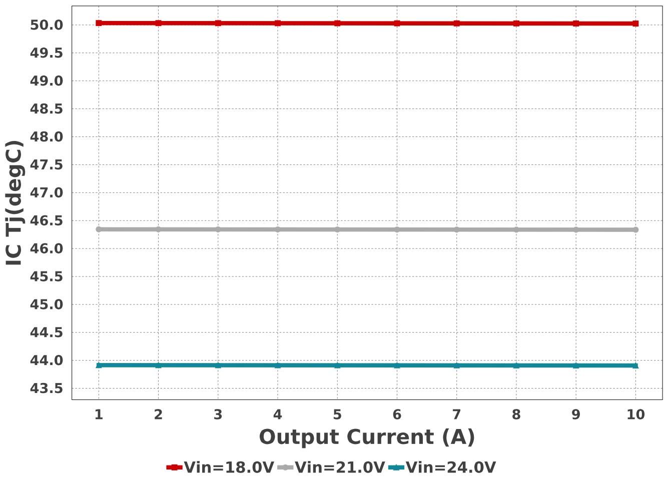
The LM5122-Q1 is qualified for Automotive applications. All passives and other components selected in this design may not be qualified for Automotive applications. The user is required to verify that all components in the design meet the qualification and safety requirements for their specific application.

Electrical BOM

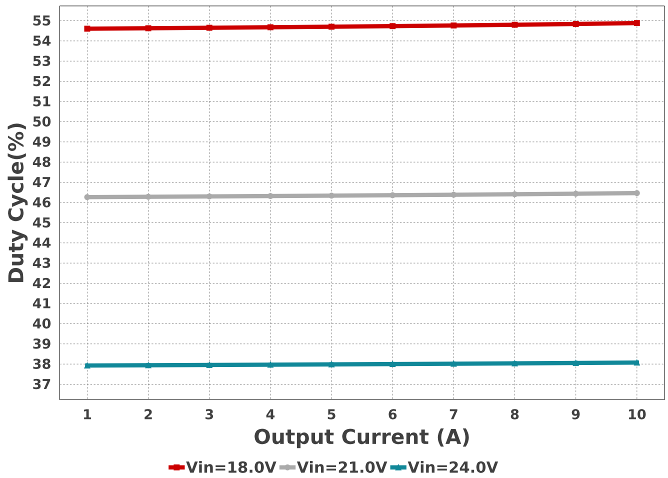
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cbst	Taiyo Yuden	MSASU21GSB7105KTNA01 Series= X7R	Cap= 1.0 uF ESR= 34.521 mOhm VDC= 50.0 V IRMS= 1.26652 A	1	$0.04	0805 7 mm^2
Ccomp	Kemet	C1210C224J3GACTU Series= C0G/NP0	Cap= 220.0 nF VDC= 5.0 V IRMS= 0.0 A	1	$1.63	1210 15 mm^2
Ccomp2	TDK	CGA4C2C0G1H392J060AA Series= C0G/NP0	Cap= 3.9 nF VDC= 50.0 V IRMS= 0.0 A	1	$0.04	0805 7 mm^2
Cin	Panasonic	35SVPF39M Series= SVPF	Cap= 39.0 uF ESR= 30.0 mOhm VDC= 35.0 V IRMS= 2.8 A	1	$0.67	CAPSMT_62_E7 106 mm^2
Cout	Panasonic	EEHZA1J560P Series= ZA	Cap= 56.0 uF ESR= 30.0 mOhm VDC= 63.0 V IRMS= 1.8 A	10	$0.93	Panasonic_G 151 mm^2
Coutx	TDK	CKG57NX7R1H476M500JH Series= X7R	Cap= 47.0 uF ESR= 16.649 mOhm VDC= 50.0 V IRMS= 0.0 A	1	$5.07	2220 54 mm^2
Cres	Taiyo Yuden	TMK212BJ474KD-T Series= X5R	Cap= 470.0 nF ESR= 1.0 mOhm VDC= 20.0 V IRMS= 0.0 A	1	$0.02	0805 7 mm^2

Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Css	MuRata	GRM155R71A273KA01D Series= X7R	Cap= 27.0 nF ESR= 1.0 mOhm VDC= 10.0 V IRMS= 0.0 A	1	$0.01	0402 3 mm²
Cvcc	MuRata	GRM21BR61C106KE15L Series= X5R	Cap= 10.0 uF ESR= 4.127 mOhm VDC= 16.0 V IRMS= 2.46634 A	1	$0.03	0805 7 mm²
Cvin	TDK	C1005X5R1V474K050BC Series= X5R	Cap= 470.0 nF ESR= 18.79 mOhm VDC= 35.0 V IRMS= 0.0 A	1	$0.02	0402 3 mm²
Dbst	SMC Diode Solutions	SK215ATR	VF@Io= 950.0 mV VRRM= 150.0 V	1	$0.06	SMA 37 mm²
L1	Coilcraft	AGP4233-223ME	L= 22.0 µH 2.95 mOhm	1	$7.84	AGP4233_Mid 1671 mm²
M1	Texas Instruments	CSD18540Q5B	VdsMax= 60.0 V IdsMax= 200.0 Amps	2	$0.75	DNK0008A 56 mm²
M2	Texas Instruments	CSD18533Q5A	VdsMax= 60.0 V IdsMax= 200.0 Amps	2	$0.33	DQJ0008A 55 mm²
Rcomp	Vishay-Dale	CRCW04024K42FKED Series= CRCW..e3	Res= 4.42 kOhm Power= 63.0 mW Tolerance= 1.0%	1	$0.01	0402 3 mm²
Rfbb	Yageo	RC0603FR-071K6L Series= ?	Res= 1.6 kOhm Power= 100.0 mW Tolerance= 1.0%	1	$0.01	0603 5 mm²
Rfbt	Vishay-Dale	CRCW040246K4FKED Series= CRCW..e3	Res= 46.4 kOhm Power= 63.0 mW Tolerance= 1.0%	1	$0.01	0402 3 mm²
Rsense	Stackpole Electronics Inc	CSNL1206FT2L00 Series= CSNL	Res= 2.0 mOhm Power= 1.0 W Tolerance= 1.0%	1	$0.19	1206 11 mm²
Rslope	Vishay-Dale	CRCW0402392KFKED Series= CRCW..e3	Res= 392.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	$0.01	0402 3 mm²
Rt	Vishay-Dale	CRCW040243K2FKED Series= CRCW..e3	Res= 43.2 kOhm Power= 63.0 mW Tolerance= 1.0%	1	$0.01	0402 3 mm²
Ruvb	Vishay-Dale	CRCW04024K22FKED Series= CRCW..e3	Res= 4.22 kOhm Power= 63.0 mW Tolerance= 1.0%	1	$0.01	0402 3 mm²
Ruvt	Vishay-Dale	CRCW040249K9FKED Series= CRCW..e3	Res= 49.9 kOhm Power= 63.0 mW Tolerance= 1.0%	1	$0.01	0402 3 mm²
Rvin	Vishay-Dale	CRCW06033R01FKEA Series= CRCW..e3	Res= 3.01 Ohm Power= 100.0 mW Tolerance= 1.0%	1	$0.01	0603 5 mm²
U1	Texas Instruments	LM5122QMH/NOPB	Switcher	1	$2.76	MXA20A 71 mm²

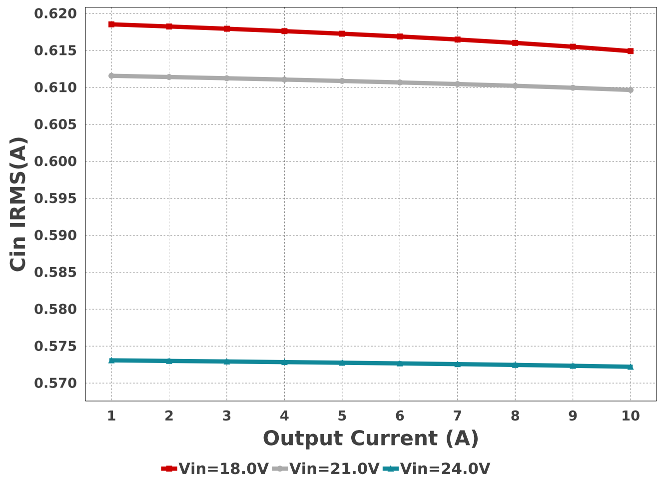
IC Tj



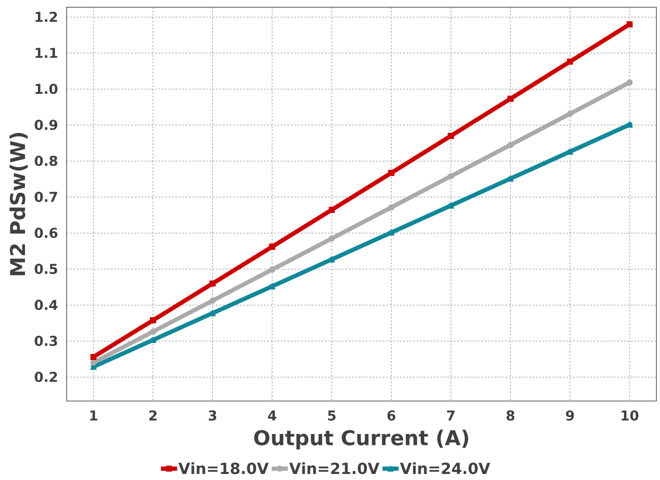
Duty Cycle



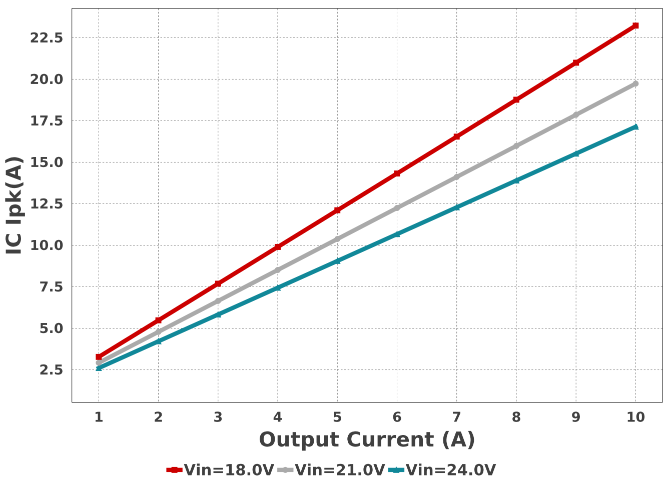
Cin IRMS



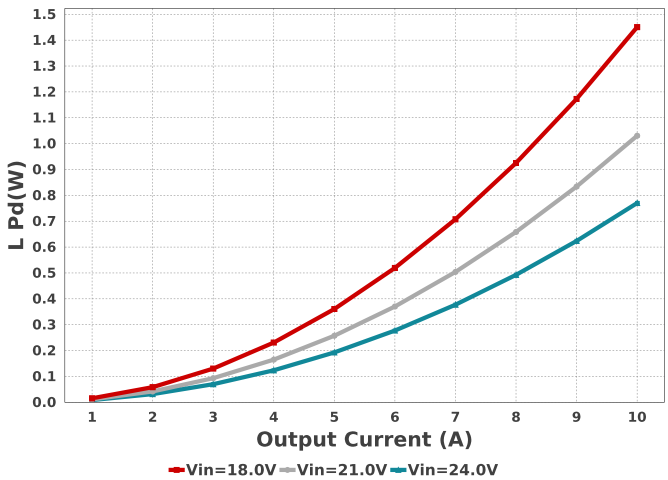
M2 PdSw



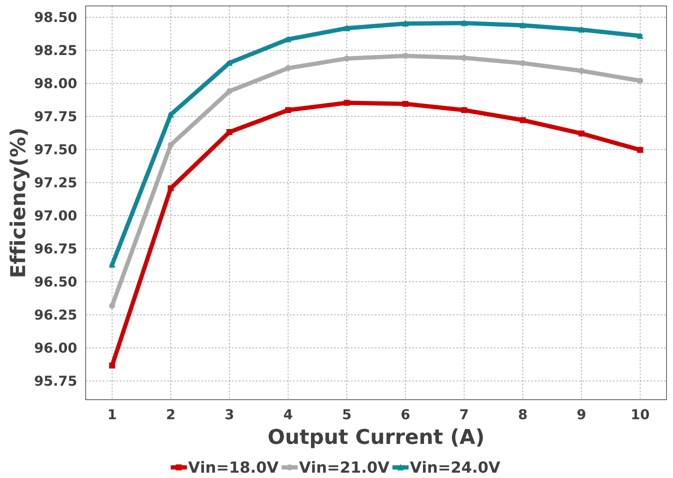
IC Ipk



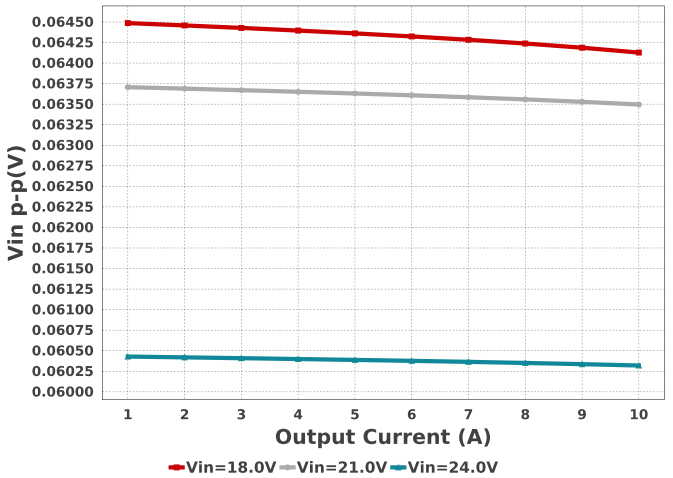
L Pd



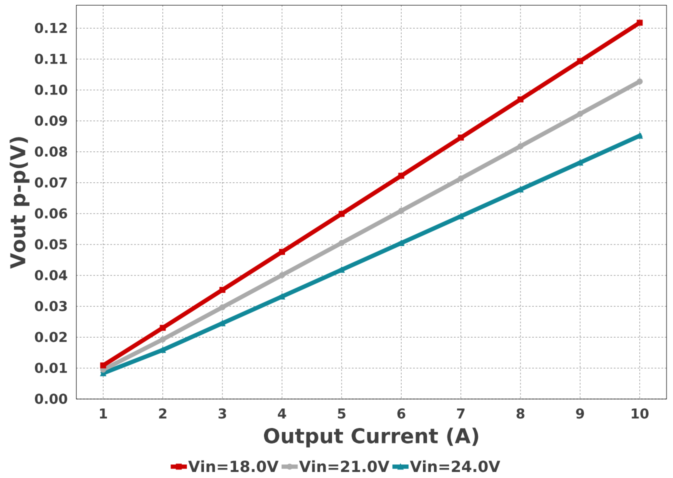
Efficiency



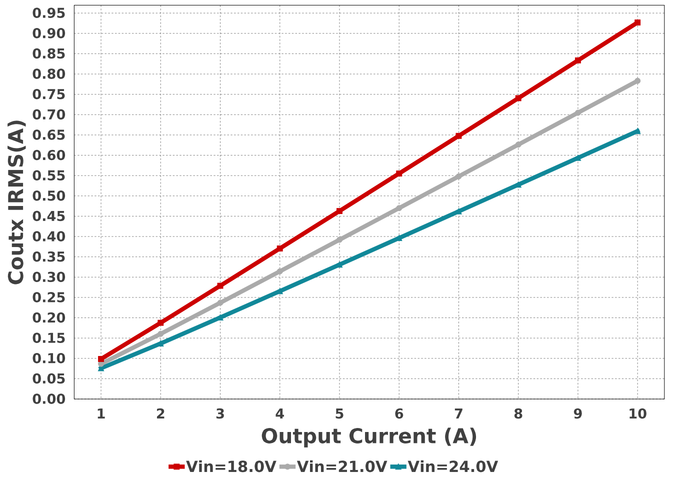
Vin p-p



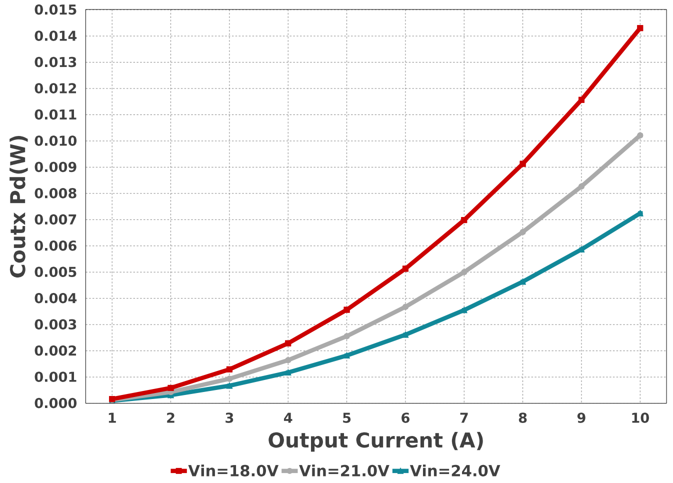
Vout p-p



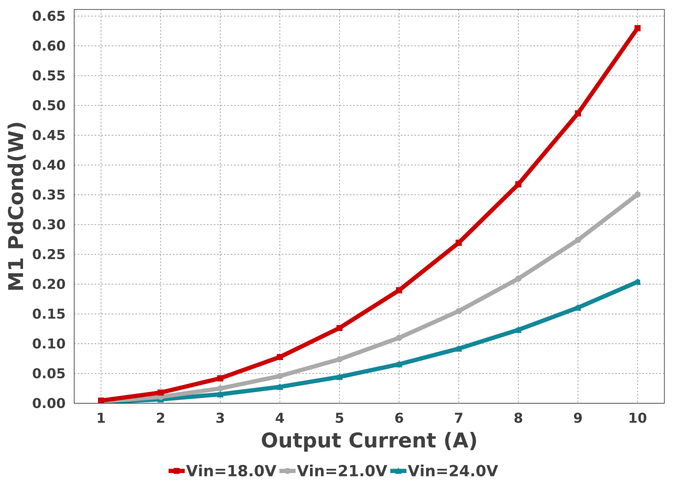
Coutx IRMS

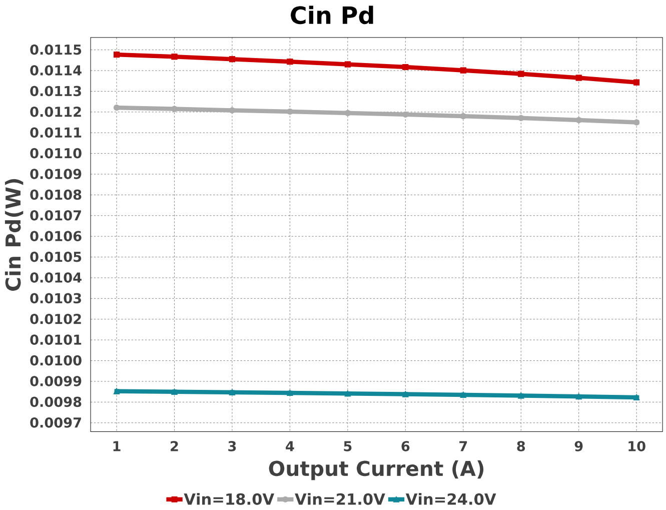


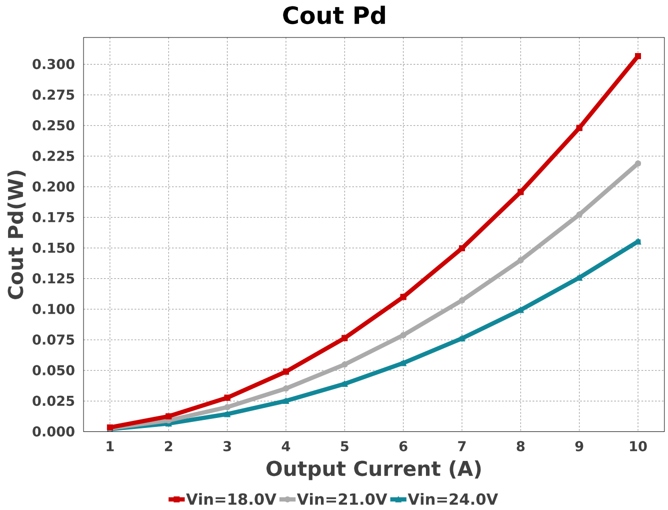
Coutx Pd

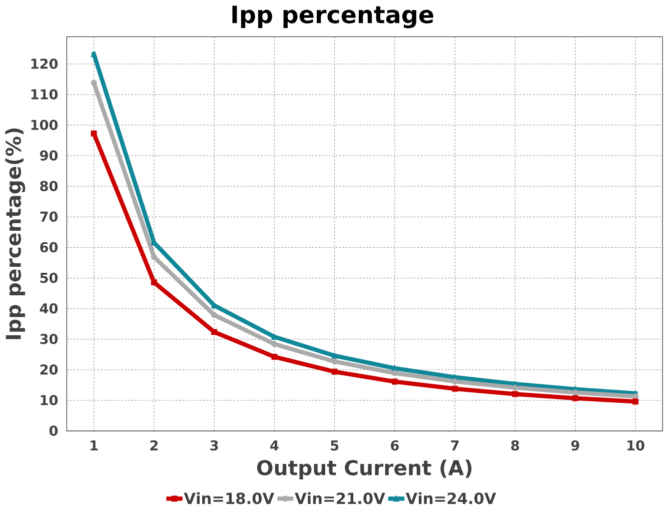


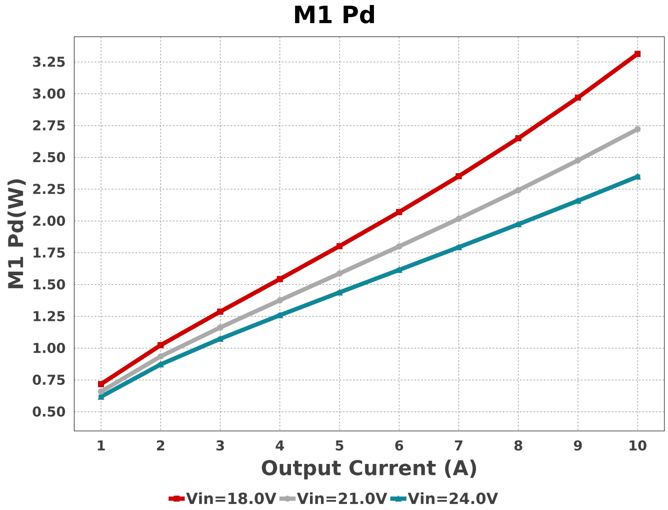
M1 PdCond

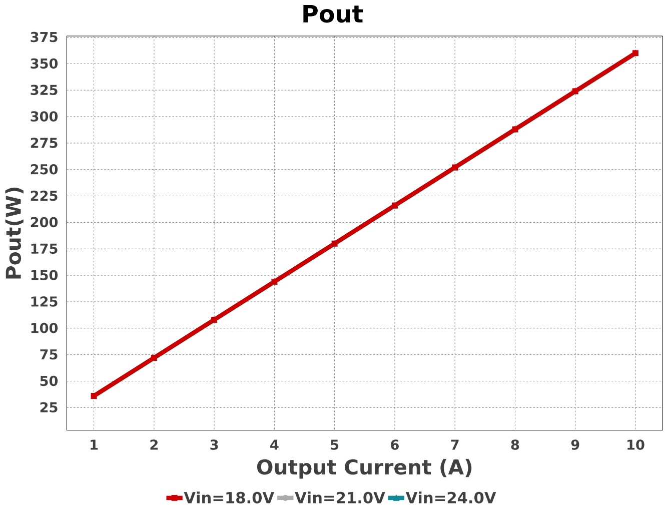


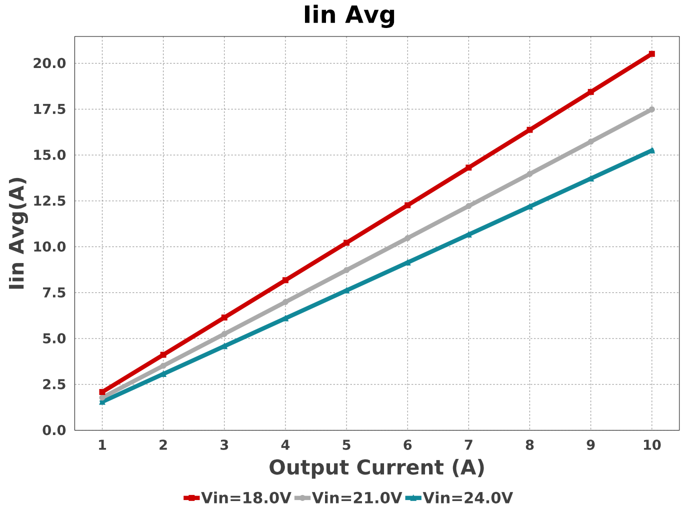

Cin Pd
Cin Pd(W)
0.0115
0.0114
0.0113
0.0112
0.0111
0.0110
0.0109
0.0108
0.0107
0.0106
0.0105
0.0104
0.0103
0.0102
0.0101
0.0100
0.0099
0.0098
0.0097
1 2 3 4 5 6 7 8 9 10
Output Current (A)
Vin=18.0V Vin=21.0V Vin=24.0V

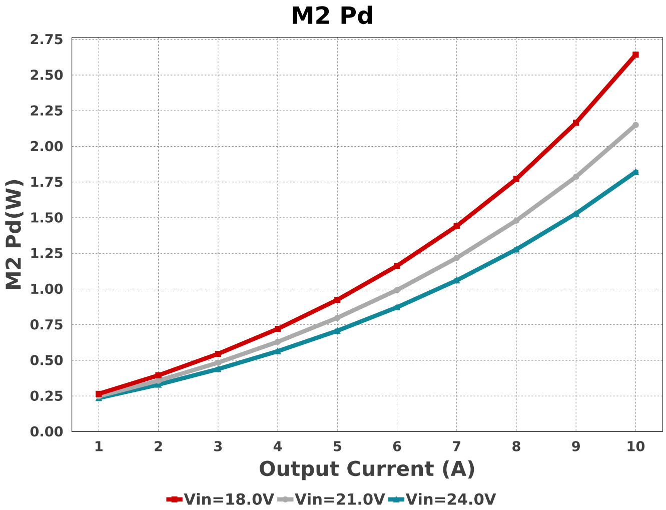

Cout Pd
Cout Pd(W)
0.300
0.275
0.250
0.225
0.200
0.175
0.150
0.125
0.100
0.075
0.050
0.025
0.000
1 2 3 4 5 6 7 8 9 10
Output Current (A)
Vin=18.0V Vin=21.0V Vin=24.0V

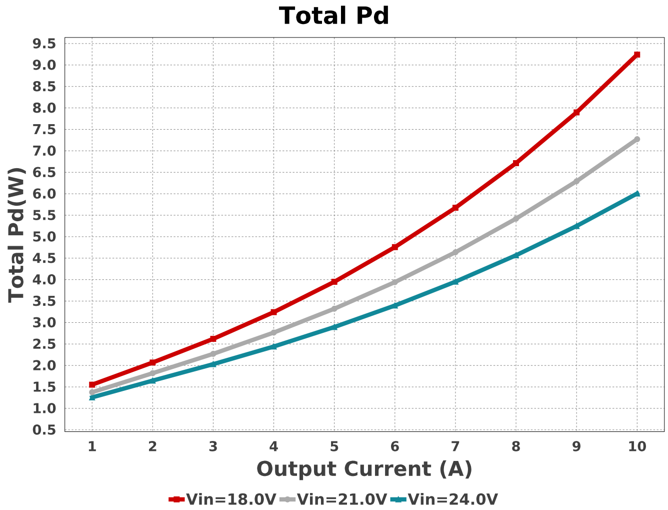

Ipp percentage
Ipp percentage(%)
120
110
100
90
80
70
60
50
40
30
20
10
0
1 2 3 4 5 6 7 8 9 10
Output Current (A)
Vin=18.0V Vin=21.0V Vin=24.0V

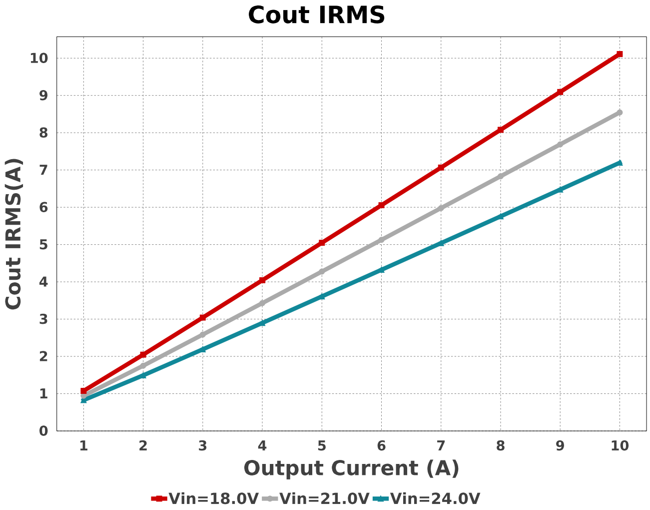

M1 Pd
M1 Pd(W)
3.25
3.00
2.75
2.50
2.25
2.00
1.75
1.50
1.25
1.00
0.75
0.50
1 2 3 4 5 6 7 8 9 10
Output Current (A)
Vin=18.0V Vin=21.0V Vin=24.0V

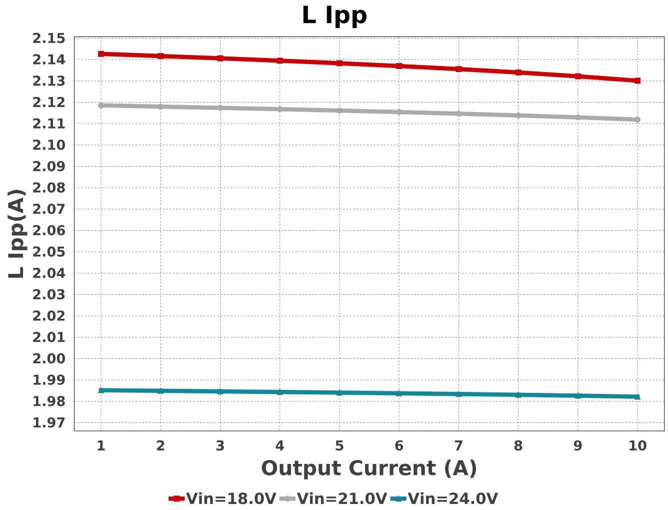

Pout
Pout(W)
375
350
325
300
275
250
225
200
175
150
125
100
75
50
25
1 2 3 4 5 6 7 8 9 10
Output Current (A)
Vin=18.0V Vin=21.0V Vin=24.0V

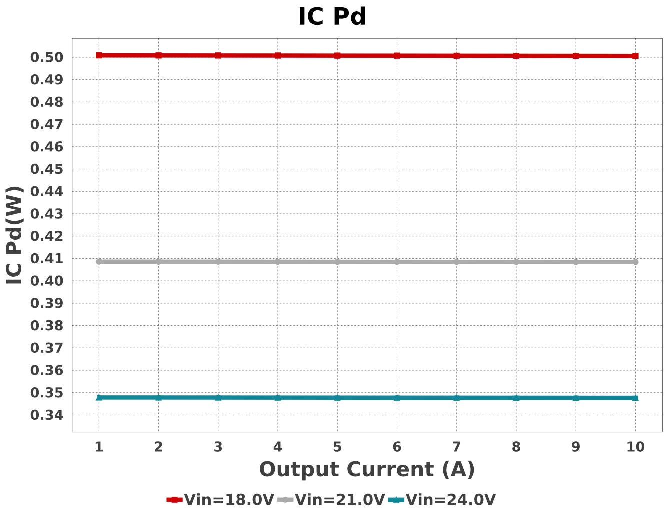

Iin Avg
Iin Avg(A)
20.0
17.5
15.0
12.5
10.0
7.5
5.0
2.5
0.0
1 2 3 4 5 6 7 8 9 10
Output Current (A)
Vin=18.0V Vin=21.0V Vin=24.0V

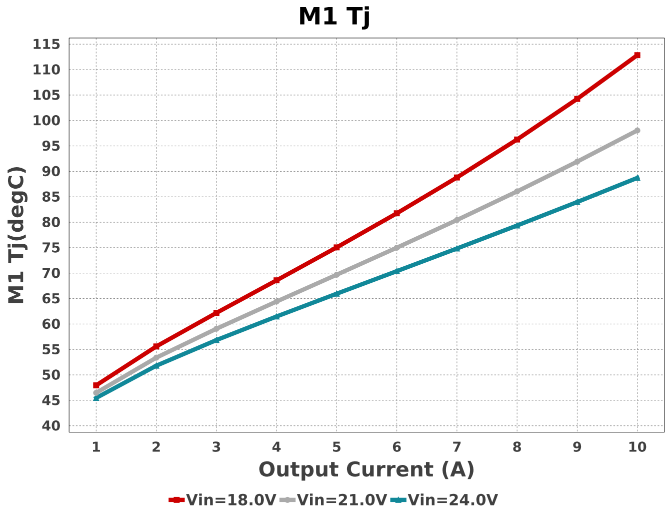

M2 Pd
M2 Pd(W)
Output Current (A)
Vin=18.0V Vin=21.0V Vin=24.0V

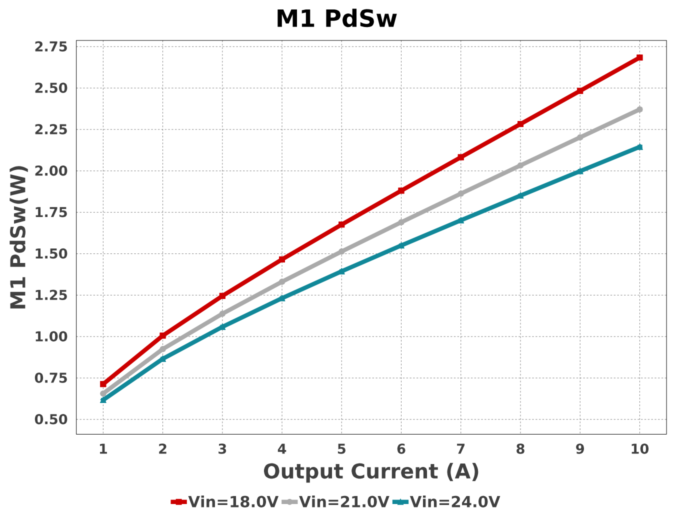

Total Pd
Total Pd(W)
Output Current (A)
Vin=18.0V Vin=21.0V Vin=24.0V

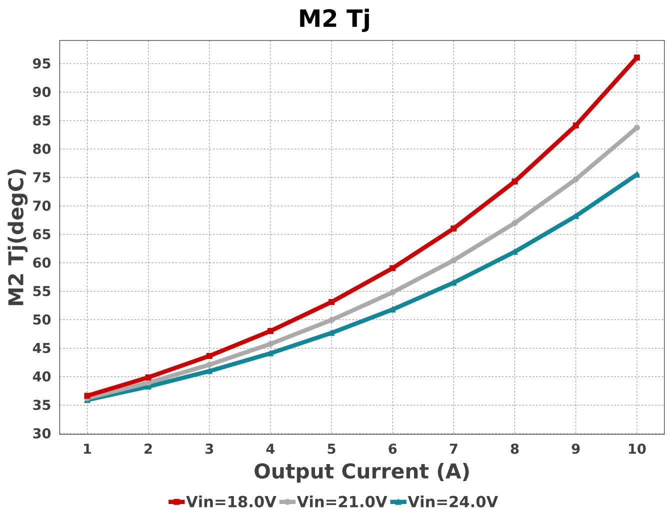

Cout IRMS
Cout IRMS(A)
Output Current (A)
Vin=18.0V Vin=21.0V Vin=24.0V

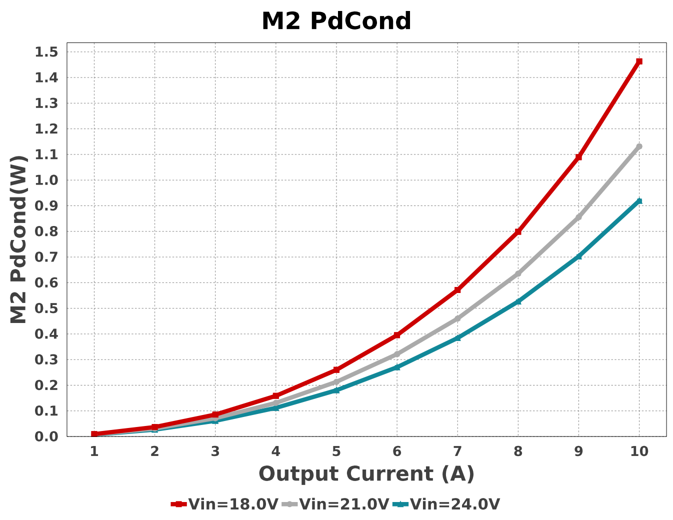

L Ipp
L Ipp(A)
Output Current (A)
Vin=18.0V Vin=21.0V Vin=24.0V

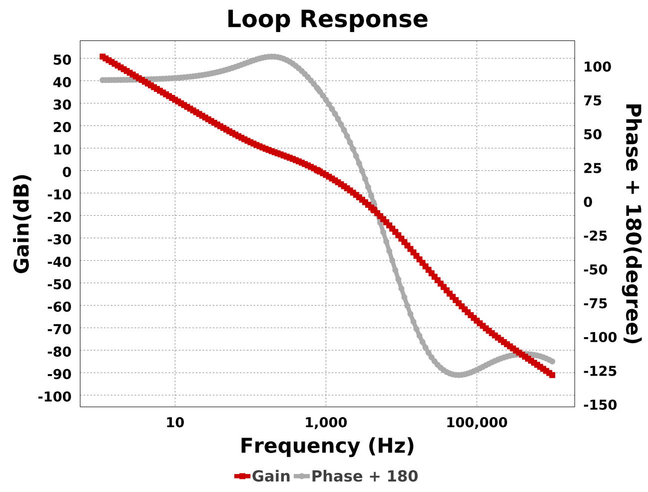

IC Pd
IC Pd(W)
Output Current (A)
Vin=18.0V Vin=21.0V Vin=24.0V


M1 Tj
M1 Tj(degC)
Output Current (A)
Vin=18.0V Vin=21.0V Vin=24.0V









Operating Values

#	Name	Value	Category	Description
1.	Cin IRMS	614.908 mA	Capacitor	Input capacitor RMS ripple current
2.	Cin Pd	11.343 mW	Capacitor	Input capacitor power dissipation
3.	Cout IRMS	10.11 A	Capacitor	Output capacitor RMS ripple current
4.	Cout Pd	306.66 mW	Capacitor	Output capacitor power dissipation
5.	Coutx IRMS	926.829 mA	Capacitor	Output capacitor_x RMS ripple current
6.	Coutx Pd	14.302 mW	Capacitor	Output capacitor_x power loss
7.	IC Ipk	23.23 A	IC	Peak switch current in IC
8.	IC Pd	500.62 mW	IC	IC power dissipation
9.	IC Tj	50.025 degC	IC	IC junction temperature
10.	IC Tolerance	18.0 mV	IC	IC Feedback Tolerance
11.	ICThetaJA	40.0 degC/W	IC	IC junction-to-ambient thermal resistance
12.	Iin Avg	20.512 A	IC	Average input current
13.	Ipp percentage	9.61 %	Inductor	Inductor ripple current percentage (with respect to average inductor current)
14.	L Ipp	2.13 A	Inductor	Peak-to-peak inductor ripple current
15.	L Pd	1.45 W	Inductor	Inductor power dissipation
16.	M1 Pd	3.314 W	Mosfet	M1 MOSFET total power dissipation
17.	M1 PdCond	629.69 mW	Mosfet	M1 MOSFET conduction losses
18.	M1 PdSw	2.684 W	Mosfet	M1 MOSFET switching losses
19.	M1 Tj	112.84 degC	Mosfet	M1 MOSFET junction temperature
20.	M2 Pd	2.643 W	Mosfet	M2 MOSFET total power dissipation
21.	M2 PdCond	1.463 W	Mosfet	M2 MOSFET conduction losses
22.	M2 PdSw	1.18 W	Mosfet	M2 MOSFET switching losses
23.	M2 Tj	96.073 degC	Mosfet	M2 MOSFET junction temperature
24.	Cin Pd	11.343 mW	Power	Input capacitor power dissipation
25.	Cout Pd	306.66 mW	Power	Output capacitor power dissipation
26.	Coutx Pd	14.302 mW	Power	Output capacitor_x power loss
27.	IC Pd	500.62 mW	Power	IC power dissipation
28.	L Pd	1.45 W	Power	Inductor power dissipation
29.	M1 Pd	3.314 W	Power	M1 MOSFET total power dissipation
30.	M1 PdCond	629.69 mW	Power	M1 MOSFET conduction losses
31.	M1 PdSw	2.684 W	Power	M1 MOSFET switching losses

#	Name	Value	Category	Description
32.	M2 Pd	2.643 W	Power	M2 MOSFET total power dissipation
33.	M2 PdCond	1.463 W	Power	M2 MOSFET conduction losses
34.	M2 PdSw	1.18 W	Power	M2 MOSFET switching losses
35.	Total Pd	9.223 W	Power	Total Power Dissipation
36.	BOM Count	35	System Information	Total Design BOM count
37.	Cross Freq	584.562 Hz	System Information	Bode plot crossover frequency
38.	Duty Cycle	54.884 %	System Information	Duty cycle
39.	Efficiency	97.502 %	System Information	Steady state efficiency
40.	FootPrint	3.761 k mm^2	System Information	Total Foot Print Area of BOM components
41.	Frequency	208.333 kHz	System Information	Switching frequency
42.	Gain Marg	-16.599 dB	System Information	Bode Plot Gain Margin
43.	Iout	10.0 A	System Information	Iout operating point
44.	Low Freq Gain	51.666 dB	System Information	Gain at 1Hz
45.	Mode	CCM	System Information	Conduction Mode
46.	Phase Marg	80.823 deg	System Information	Bode Plot Phase Margin
47.	Pout	360.0 W	System Information	Total output power
48.	Total BOM	$29.93	System Information	Total BOM Cost
49.	Vin	18.0 V	System Information	Vin operating point
50.	Vin p-p	64.128 mV	System Information	Peak-to-peak input voltage
51.	Vout	36.0 V	System Information	Operational Output Voltage
52.	Vout Actual	36.0 V	System Information	Vout Actual calculated based on selected voltage divider resistors
53.	Vout Tolerance	3.482 %	System Information	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
54.	Vout p-p	121.767 mV	System Information	Peak-to-peak output ripple voltage

Design Inputs

Name	Value	Description
Iout	10.0	Maximum Output Current
VinMax	24.0	Maximum input voltage
VinMin	18.0	Minimum input voltage
Vout	36.0	Output Voltage
base_pn	LM5122-Q1	Base Product Number
source	DC	Input Source Type
Ta	30.0	Ambient temperature

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of Cin and Cout, and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

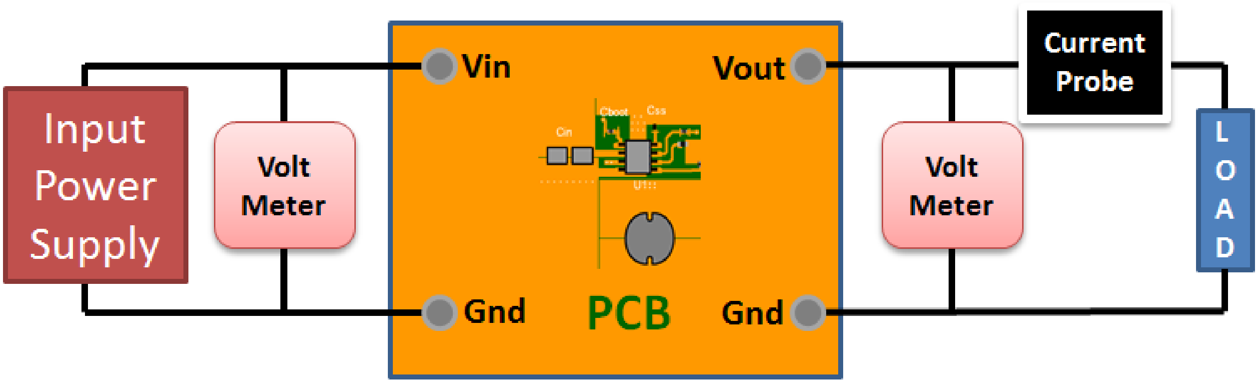
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 18.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to Vin and GND. Connect a digital volt meter and a load if needed to set the minimum Iout of the design from Vout and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between Vin and GND, a load is connected between Vout and GND and a current meter is connected in series between Vout and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



Design Assistance

1. The LM5122 is a wide range boost controller which is operable in an ultra wide input range of 4.5 to 65V. A boost regulator can maintain regulation for input voltages lower than the output voltage.

2. Feature Highlights: Automotive Qualified 12V to 14V Vin, 24Vout, 2A as typical design input conditions

3. The LM5122-Q1 is qualified for Automotive applications. All passives and other components selected in this design may not be qualified for Automotive applications. The user is required to verify that all components in the design meet the qualification and safety requirements for their specific application

4. Master key : FF65EAF3001A9529E4D1AF68526A0C6D[v1]

5. **LM5122-Q1** Product Folder : http://www.ti.com/product/LM5122%2DQ1 : contains the data sheet and other resources.